





# Flanged Attenuators 50 Watts



# **General Specifications**

Resistive Element Thick film

Substrate Beryllium oxide ceramic

Cover Alumina Ceramic

**Lead(s)** 99.99% pure Silver (.005" thk)

**Mounting Flange** Copper, Nickel plated per QQ-N-290

Operating Temperature -55 to +150°C (see chart)

#### Features:

- DC 2.5 GHz
- 50 Watts
- BeO Ceramic
- Welded Silver Leads
- Non-Nichrome Resistive Element
- Low VSWR
- 100% Tested

#### **Electrical Specifications**

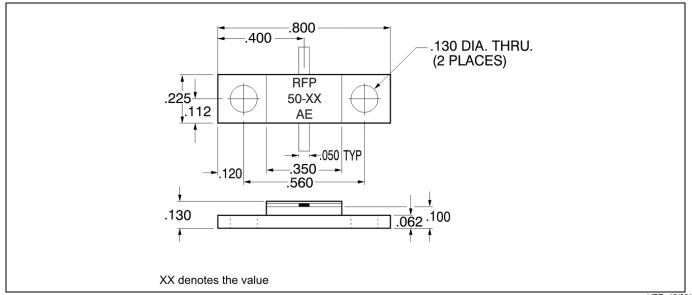
**Attenuation Value:** 1, 2, 3, 4, 5, 6, 9, 10, 20 or 30 dB

Power: 50 Watts Frequency Range: DC – 2.5 GHz

**Notes:** Tolerance is  $\pm 0.010$ ", unless otherwise specified. Designed to meet of exceed applicable portions of MIL-E-5400. All dimensions in inches. Lead length 0.150" minimum. Specification based on unit properly installed using suggested mounting instructions and a 50 ohm nominal impedance.

Specifications subject to change without notice.

# **Outline Drawing**



VER. 12/08/05



USA/Canada: Toll Free: Europe:

(315) 432-8909 (800) 544-2414 +44 2392-232392

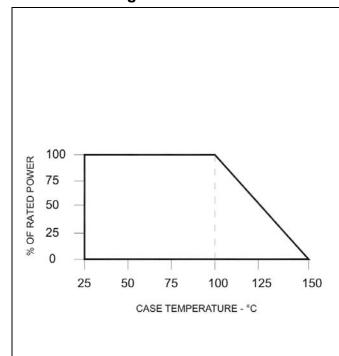


## **Specifications**

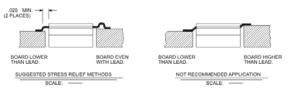
PART NUMBER	ATTENUATION(dB)	TOL. (±dB)	POWER (WATTS)	VSWR	FREQ (GHZ)
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RFP-50-1AE	1	0.75	50	1.50:1	2.0
RFP-50-2AE	2	0.50	50	1.30:1	2.0
RFP-50-3AE	3	0.50	50	1.30:1	2.0
RFP-50-4AE	4	0.50	50	1.20:1	2.0
RFP-50-5AE	5	0.50	50	1.20:1	2.0
RFP-50-6AE	6	0.50	50	1.20:1	2.0
RFP-50-9AE	9	0.50	50	1.20:1	2.0
RFP-50-10AE	10	0.50	50	1.25:1	2.0
RFP-50-20AE	20	0.50	50	1.20:1	2.5
RFP-50-30AE	30	0.50	50	1.20:1	1.7

#### **Power Derating**

# **Suggested Mounting Procedures**



## Suggested Mounting Procedure



- Make sure that the devices are mounted on flat surfaces (.001" under the device) to optimize the heat transfer.
- ${\bf 2.}$  Drill & tap the heatsink for the appropriate thread size to be used.
- Coat heatsink with a minimum amount of high quality silicone grease (.001" max. thickness).
- 4. Position device on mounting surface and secure using socket head screws, flat & split washers. Torque screws to the appropriate value. Make sure that the device is flat against the heatsink. (Care should be taken to avoid upward pressure of the leads towards the lid).
- Solder leads in place using an SN63 type solder with a controlled temperature iron (210°C).

